

LIQUID CRYSTAL DISPLAY DEVICE

BACKGROUND OF THE INVENTION

1. Field of the Invention

5 The present invention relates to a liquid crystal display device, and more particularly to a liquid crystal display device which has a structure in which a gate signal is directly applied to a gate line by an integrated printed circuit board without any gate printed circuit board.

2. Description of the Related Art

10 A liquid crystal display device applies a voltage to a molecular arrangement of a liquid crystal to convert the molecular arrangement to another molecular arrangement. The liquid crystal display device converts the changes of the optical properties of liquid crystal cells which emits light according to the molecular arrangement, and uses the modulation of the light of the liquid crystal cells.

15 The liquid crystal display device includes a liquid crystal panel to which electrical signal are applied to determine whether the light has been passed. The liquid crystal panel is a passive light device, and a back light assembly for providing the liquid crystal display device with the light is attached to the rear surface of the liquid crystal panel. A source part for applying screen data to display the screen and a gate part for applying
20 gate signals for driving the gate device of a thin film transistor of the liquid crystal panel are attached to the liquid crystal panel. An electrical signal is applied to the liquid crystal of the liquid crystal panel by applying a picture signal to the transistor of the liquid crystal panel through the source part and the gate part, and the light from the back light

assembly is regulated to constitute a screen.

The method for connecting the liquid crystal panel to the source and gate driving IC is sorted into a COG (Chip-On Glass) type and a TAB (Tape Automated Bonding) type. According to the COG type, a driving IC of a semiconductor package type is
5 directly mounted to the gate and data areas of the liquid crystal panel, to transfer the electrical signals to the liquid crystal panel. The driving IC uses an anisotropic conductive film, and is bonded to the liquid crystal panel.

According to the TAB type, the liquid crystal panel is directly connected to the printed circuit board by using a tape carrier package to which the driving IC is mounted.

10 One end of the tape carrier package is connected to the liquid crystal panel, and the other end of the tape carrier package is connected to the printed circuit board. Then, the input wire of the carrier package is connected to the output pad of the printed circuit board by soldering or using an anisotropic conductive film.

Examples of the liquid crystal panel modules which use the tape carrier package
15 are disclosed in U.S. Patent No. 5,572,346 issued to Sakamoto et al. And U.S. Patent No. 6,061,246 issued to Oh et al. The conventional TFT liquid crystal modules mainly use the tape carrier package to mount the driving IC.

Recently, LCD modules of various structures have been developed to slim the LCD module. Especially, considering the LCD modules are used in portable computers,
20 the light weight of the LCD module is important. If the tape carrier package is applied to the LCD modules, the flexibility is insufficient. Therefore, a flexible circuit board is used in an LCD module. A COF (Chip On Film) method is used to mount the driving IC to the flexible circuit board. According to the COF method, a chip is mounted onto the printed

circuit board by using a TAB.

Since the weight and the volume of the liquid crystal device is increased as the size of the screen becomes larger, an effort to reduce the area and the volume which is occupied by a portion except for the screen has been processed. For example, an U.S. patent application No. 09/551,404 which was filed on April 17, 2000, is pending with USPTO and corresponds to Korean Patent Application No. 99-13650 discloses a liquid crystal display device which removes the gate printed circuit board which increases the thickness of the liquid crystal display panel.

A circuit of the gate portion of the liquid crystal display device is removed to reduce the volume and the weight of the liquid crystal display device. However, since the gate tape carrier package is bent towards the rear surface of the mold frame into which the liquid crystal display panel is received and is attached to the rear surface of the mold frame, the height of the liquid crystal display device is increased according to the position of the driving IC which is mounted to the gate tape carrier package.

SUMMARY OF THE INVENTION

The present invention has been made to solve the above-mentioned problem, and accordingly it is an object of the present invention to provide a liquid crystal display device in which an integrated printed circuit board is manufactured by integrating a circuit of a gate portion with a source portion and is located on the source side of the liquid crystal panel, and a flexible circuit board according to the COF method is provided on the gate side, and the flexible circuit board is supported towards a mold frame to reduce the area and the volume which is occupied by a portion except for a

screen.

In order to achieve the above-mentioned object of the present invention, the present invention provides a liquid crystal display device which has a display unit which comprises a liquid crystal display panel, and a flexible circuit board which is attached to one side of the liquid crystal display panel, for transferring driving signals for driving the liquid crystal panel. A back light assembly provides a light to the display unit. A mold frame receives the liquid crystal display panel and the back light assembly. A chassis is coupled to the mold frame and combines the liquid crystal display panel with the backlight assembly. A support means supports the flexible circuit board for transferring the driving signal to the liquid crystal display panel towards the mold frame.

Since the gate side flexible circuit board is easily supported by the support means towards the mold frame, the planar increasing of the liquid crystal display device is prevented.

BRIEF DESCRIPTION OF THE DRAWINGS

The above and other objects and advantages of the present invention will become readily apparent by reference to the following detailed description when considered in conjunction with the accompanying drawings wherein:

FIG. 1 is an exploded perspective view for showing a liquid crystal display device according to a preferred embodiment of the present invention;

FIG. 2 is a perspective view for showing the engaging state of a flexible circuit board separating support member of a mold frame according to the present invention;

FIG. 3 is a perspective view for showing of a flexible circuit board separating

support member according to the present invention;

FIG. 4 is a cross-sectional view for showing the separating support member of FIG. 3 which is adhered to a flexible circuit board;

FIG. 5 is a cross-sectional view for showing the engaging state of the flexible circuit board according to the second preferred embodiment of the present invention and a mold frame;

FIG. 6 is a cross-sectional view for showing the engaging state of a fixing film of FIG. 5 in case a catching boss is provided on the bottom surface of a mold frame;

FIG. 7 is a cross-sectional view for showing the engagement of the fixing film of FIG. 5 in case the length of the bent flexible circuit board is shorter than the length of the side wall of the mold frame;

FIG. 8 is a preferred embodiment of a fixing film in which the number of the end portions attached to a chassis is identical with the number of receiving recesses;

FIG. 9 is a cross-sectional view for showing the engaging state of a resilient member which is located in a space between the bottom surface of a flexible circuit board and the inner side surface of a chassis;

FIG. 10 is an exploded perspective view for showing a liquid crystal display device including a printed circuit board cover;

FIG. 11 is a cross-sectional view for showing a chassis of a portion which corresponds to a portion in which a flexible circuit board is formed;

FIG. 12 is a cross-sectional view for showing a flexible circuit board portion of a liquid crystal display device which is assembled by using the chassis of FIG. 10; and

FIG. 13 is a cross-sectional view for showing a state in which a flexible circuit

board is supported towards the mold frame according to a preferred embodiment of the present invention.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

5 Hereinafter, preferred embodiments of the present invention will be explained in detail with reference to the attached drawings.

Embodiment 1

FIG. 1 is an exploded perspective view for schematically showing a liquid crystal
10 display device according to the first preferred embodiment of the present invention.

Referring to FIG. 1, a liquid crystal display device 600 has a liquid crystal display module 700 to which image signals are applied for displaying a screen, a front case 800 for receiving the liquid crystal display module 700, and a rear case 900.

The liquid crystal display module 700 has a display unit 710 which comprises a
15 liquid crystal display panel which displays the screen.

The display unit 710 includes a liquid crystal display panel 712, an integrated printed circuit board 714, and a data side tape carrier package 716, and a gate side flexible circuit board 718 which is manufactured by the COF method.

The liquid crystal display panel 712 includes a thin film transistor substrate 712a,
20 a color filter substrate 712b, and a liquid crystal (not shown).

The thin film transistor substrate 712a is a transparent glass substrate on which thin film transistors of the matrix type are formed. A data line is connected to a source terminal of the thin film transistors, and a gate line is connected to a gate terminal of the

thin film transistors. A pixel electrode comprised of indium tin oxide which is a transparent conductive material is formed in a drain terminal.

When electrical signals are inputted to the data line and the gate line, the electrical signals are inputted to the source terminal and the gate terminal of the thin film transistors. The thin film transistors are turned on and off by the electrical signals. Electrical signals which is needed to form pixels are outputted to the drain terminal.

A color filter substrate 712b is opposite to the thin film transistor substrate 172a. The color filter substrate 712b is a substrate in which an RGB pixel which is a color pixel which emits a color when a light passes through it is formed by a thin film process. A common electrode comprised of ITO is coated on the front surface of the color filter substrate 712b.

If an electric power is applied to the gate terminal and the source terminal of the transistor of the thin film transistor substrate 712a and the thin film transistor is turned on, an electric field is formed between the pixel electrode and the common electrode of the color filter substrate. The arranging angle of a liquid crystal which is injected between the thin film transistor substrate 712a and the color filter substrate 714b is changed by the electric field, and the light transmittance rate is changed according to the changed arranging angle, and a desired pixel is obtained.

A driving signal and a timing signal are applied to the gate line and the data line of the thin film transistor to control the arranging angle of the liquid crystal of the liquid crystal display panel 712 and the time at which the liquid crystal is arranged. A data tape carrier package 716 which is a flexible circuit board which determines the time for applying the data driving signal is attached to the source side of the liquid crystal

display panel 712, and a gate side flexible circuit board 718 which is manufactured by the COF method for determining the time for applying the driving signal of the gate is attached to the gate side of the liquid crystal display panel 712.

5 The integrated printed circuit board 714 for receiving image signals from the outside of the liquid crystal display panel 712 and applying driving signals to the gate line and the data line is connected to the data tape carrier package 714 of the data line side of the liquid crystal display panel 712. The integrated printed circuit board 714 includes a source part to which the image signals which are generated at an exterior information processing device (not shown) are applied to provide data driving signals to
10 the liquid crystal display panel 712 and a gate part for providing gate driving signals to the gate line. The integrated printed circuit board 714 generates the gate driving signals for driving the liquid crystal display device, the data signals, and a plurality of timing signals for applying the gate driving signals and the data signals at a proper time. The gate driving signals are applied to the gate line of the liquid crystal display panel 712
15 through the gate side flexible circuit board 718, and the data signals are applied to the data line of the liquid crystal display panel 712 through the data tape carrier package 716.

A back light assembly 720 for providing a uniform light to the display unit 710 is provided under the display unit 710. The back light assembly 720 comprises a linear
20 lamp 722 for generating a light. The linear lamp 722 is provided on one side of the liquid crystal display module 700. A light guide plate 724 has a size which corresponds to the liquid crystal panel 712 of the display unit 710. The light guide plate 724 is located under the liquid crystal panel 712, and a portion which is near the lamp 722 is

the most thickest, and the portions which are far from the lamp 722 are thinner (that is, the thickness of the light guide plate 724 gradually decreases as the distance from the lamp 722 increases). The light guide plate 724 guides the light generated in the lamp 722 towards the display unit 710, and changes the passage of the light.

5 A plurality of optical sheets 726 for making the luminosity of the light which is emitted from the light guide plate 724 and is inputted to the liquid crystal display panel 712 uniform are provided above the light guide plate 724. A reflection plate 728 for reflecting the light which is leaked from the light guide plate 724 towards the light guide plate 724 to increase the efficiency of the light is provided under the light guide plate
10 724.

The display unit 710 and the back light assembly 720 is supported by a mold frame 730 which is a receiving receptacle. The mold frame 730 has a box-shape, and the upper portion of the mold frame is opened. Namely, the mold frame 730 has four side walls and a bottom surface. The integrated printed circuit board 714 is bent along
15 the outer side surface of the mold frame, and openings for positioning the bent portion of the integrated printed circuit board 714 are formed at the bottom surface of the mold frame 730.

The integrated printed circuit board 714 of the display unit 710 and the gate tape carrier package 718 is bent to the outside of the mold frame 730, and a chassis 740
20 which is coupled to the mold frame is provided to fix the liquid crystal display panel 712 to the backlight assembly 720.

The chassis 740 has a rectangular shape like the mold frame 730. The upper portion of the chassis 740 is opened to expose the liquid crystal panel 710, and the side

wall portion of the chassis 740 is bent to the inner vertical direction to cover the peripheral portion of the upper surface of the liquid crystal panel 710.

The liquid crystal display device includes a support member for supporting the flexible circuit board for transmitting the driving signal to the liquid crystal panel toward the mold frame. In case the flexible circuit board 718 is bent towards the side wall of the mold frame 730, the support member prevents the end portion of the flexible circuit board 718 from protruding towards the bottom surface of the mold frame 730 and prevents the increasing of the planar area of the liquid crystal display device 600 by the gate driving IC which is formed in the flexible circuit board 718.

FIG. 2 is a perspective view for showing the engagement of a gate side flexible circuit board separating support member 766 and the mold frame 730, and FIG. 3 is a perspective view for showing the gate side flexible circuit board separating support member 766, and FIG. 4 is a cross-sectional view for showing the separating support member 766 which is adhered to the gate side flexible circuit board 718.

Referring to FIGS. 1 and 2, the mold frame 730 according to the preferred embodiment of the present invention is bent along the side wall of the gate side flexible circuit board 718, and includes a receiving recess 760 at a portion in which the gate driving IC makes contact with the side wall. In case the gate side flexible circuit board 718 is bent towards the side wall of the mold frame 730, the receiving recess 760 prevents the end thereof from protruding from the side wall of the mold frame 730. The mold frame 730 is inclined from the upper portion of the outer side surface thereof towards the lower end of the outer side surface. A portion of the receiving recess 760 which makes contact with the gate driving IC is formed deep to receiving the protruding

portion. Specifically, a central portion of the receiving recess 760 is formed deep by the height of the gate driving IC to receive the gate driving IC.

The inclined receiving recess 760 prevents the end portion of the gate side flexible circuit board 718 from protruding towards the outside of the mold frame 730, and restrains the increasing of the thickness of the liquid crystal display device 600 by the gate driving IC.

As shown in FIG. 2, an engaging recess 760 having a predetermined depth is formed on both sides of the inclined receiving recess 760 formed in the mold frame 730, and an engaging hole 764 having a predetermined depth is formed on the bottom surface of the engaging recess 762. Also, the separating support member 766 for restricting the movement of the position of the gate side flexible circuit board 718 is installed.

The preferred embodiment of the separating supporting member 766 is more specifically shown in FIGS. 2 and 3. The separating support member 766 comprises a body 766a of a triangular prism which has a length of the inclined surface which corresponds to the length of the inclined surface of the receiving recess 760, an engaging plate 766b which is formed at the end portion of the body 766a and adheres to the engaging recess 762, and an engaging boss 766c which is formed in the engaging plate 766b and is engaged corresponding to the engaging hole 764. The rest portions except for the inclined surface of the separating support member 766 has a recess of a predetermined depth, and thus the weight of the separating support member 766 is minimized.

As shown in FIG. 4, the inclined surface of the separating support member 766

closely supports the bottom surface of the gate side flexible circuit board 718 which is bent towards the outside of the side wall of the mold frame 730, and the gate side flexible circuit board 718 is placed into the receiving recess 760 of the mold frame 730.

After the gate side flexible circuit board 718 is fixed to the mold frame 730, the chassis 740 is engaged with the outer side of the side wall of the mold frame 730 to prevent the separating support member 766 and the display unit 710 from deviating from the mold frame 730. The chassis 740 has an L-shaped clamp like cross-section. The chassis 740 is formed by integrally engaging a horizontal portion 740a which presses the peripheral portion of the upper surface of the display unit 710 in a state in which the display area of the display unit 710 is opened and a side wall portion 740b which engages the separating support member 766 and the mold frame 730 by engaging with the side wall of the mold frame 730 and pressing the rear surface of the separating support member 766. The liquid crystal display module 700 is mounted to the front case 800 and the rear surface case 900 to form the liquid crystal display device 600.

In order to assemble the liquid crystal display device, the back light assembly 720 is positioned in the mold frame 730, and then the display unit 710 is positioned on the back light assembly 720. Then, the integrated printed circuit board 714 which is connected through the data tape carrier package 716 is bent along the outer side surface of the side wall of the mold frame 730, and is positioned in the opening portion formed in the bottom surface of the mold frame 730. Then, the chassis 740 is engaged with the mold frame 730 to fix the display unit 710 and the back light assembly 720 to the mold frame 730. Then, the gate side flexible circuit board 718 attached to the gate

side of the display unit surrounds the outer side surface of the mold frame, and is bent to be fixed to the bottom surface of the mold frame 730.

Embodiment 2

5 FIG. 5 is a cross-sectional view for showing the engaging state of a gate side flexible circuit board and a mold frame according to the second preferred embodiment of the present invention. FIG. 6 is a cross-sectional view for showing the engagement according to the second preferred embodiment of the present invention of the case in which a catching boss is formed on the bottom surface of the mold frame 730. FIG. 7 is
10 a cross-sectional view for showing the engagement of the mold frame according to the preferred embodiment of the present invention of the case in which the length of the bent flexible circuit board is shorter than the length of the side wall of the mold frame. FIG. 8 is a preferred embodiment of a fixing film which is disclosed in FIGS. 5 to 8, and the number of the end portions attached to a chassis is identical with the number of
15 receiving recesses.

In the preferred embodiment, a flexible circuit board fixing film 500 is used as a support member instead of the separating support member of the first preferred embodiment.

Referring to FIG. 5, the gate side flexible circuit board 718 is bent towards the
20 side wall of the mold frame 730, and a portion of the fixing film 500 which is longer than the width of the receiving recess 760 and the length of the gate side flexible circuit board 718 is attached to the inner side surface of the horizontal portion 740 of the chassis 740 by a bonding material or a bonding tape.

In the state in which one side end portion of the fixing film 500 is attached to the inner side surface of the chassis, the other end portion of the fixing film 500 is pulled tight and surrounds the gate side flexible circuit board 718. The fixing film 500 is fixed to the bottom surface of the outer side of the mold frame, pressing the flexible circuit
5 board 718 towards the inner side of the receiving recess. Then, a bonding material 520 can be used to fix the fixing film 500 to the bottom surface of the mold frame 730. A double sided bonding tape can be used instead of the bonding material 520.

As shown in FIG. 6, the fixing film 500 is fixed by forming a penetrating hole in the fixing film 500 which is opposite to the bottom surface of the mold frame 730 and
10 forming a catching boss 550 which is engaged with the penetrating hole in the mold frame 730. It is preferable that a bonding material 520 or a bonding tape is formed in the fixing film 500 which is opposite to the bottom surface of the mold frame 730.

Referring to FIG. 7, the gate driving IC is received in the receiving recess 760, and one end portion of the fixing film 500 is tightly fixed to the inner surface of the
15 vertical portion 740b of the chassis 740, and the fixing film 500 is fixed to the mold frame 730 with the other end of the fixing film 500 tightly pulled.

FIGS. 5 to 7 show a preferred embodiment in which the gate side flexible circuit board 718 is fixed by using the fixing film 500 which corresponds to the number of the receiving recess 760. One end of the fixing film 500 can be mutually connected in the
20 state in which the other end of the fixing film 500 corresponds to the number of the receiving recess 760, and the fixing film 500 can be attached to the bottom surface of the mold frame 730 by one process. FIG. 8 is a top view for showing a preferred embodiment of the fixing film 500 to which an end portion which is attached to the mold

frame 730 is integrally connected.

Referring to FIG. 8, an uneven portion 510 of the fixing film 500 is divided corresponding to the receiving recess 760, the gate side flexible circuit board 718 is supported towards the inner side of the receiving recess. The lower end portion 520 of the fixing film 500 is integrally formed, and can be attached to the bottom portion of the mold frame 730.

Embodiment 3

FIG. 9 is a cross-sectional view for showing the engaging state in which the flexible circuit board is engaged with the mold frame by a resilient member which is inserted into a space which is formed between the bottom surface of the flexible circuit board and the inner side surface of the chassis.

According to the preferred embodiment, the resilient member 400 of a triangular prism is inserted into the space which is formed between the bottom surface of the gate side flexible circuit board 718 and the inner side surface of the vertical portion 740b of the chassis 740 by the tight fitting to tightly fix the gate side flexible circuit board 718 to the receiving recess 760 of the mold frame 730.

Embodiment 4

FIG. 10 is an exploded perspective view for showing a liquid crystal display device which includes a printed circuit board cover according to the preferred embodiment. FIG. 11 is a cross-sectional view for showing the chassis of the portion which corresponds to a portion in which the gate side flexible circuit board is formed.

FIG. 12 is a cross-sectional view for showing a gate side flexible circuit board portion of the liquid crystal display device which is assembled by using the chassis which is shown in FIG. 11.

According to the preferred embodiment, a support member for positioning the
5 gate side flexible circuit board 718 which is bent along the side wall of the mold frame in the receiving recess 760 is provided to the chassis.

Referring to FIG. 10, a printed circuit board cover 750 is provided under the mold frame. The printed circuit board cover 750 is provided to protect the bottom portion of the data side to which the integrated printed circuit board 714 is attached and the gate
10 side bottom portion to which the gate side flexible circuit board 718 is fixed. The printed circuit board cover 750 can be manufactured by using a plastic film. The other members are identical as in the first preferred embodiment, and the explanation thereof is omitted.

Referring to FIG. 11, a resilient (or elastic) support member 780 for supporting
15 the gate side flexible circuit board 718 to the mold frame 730 is provided on the inner surface of the side wall portion 740b of the chassis 740 which corresponds to the forming portion of the gate side flexible circuit board 718.

It is preferable that the resilient support member 780 is made of a resilient material such as a rubber. Preferably, the surface of the resilient support member 780
20 is smoothly processed to prevent the damage of the gate side flexible circuit board 718. The resilient support member 780 has an L-shape, and the vertical portion of the resilient support member 780 is fixed to the inner surface of a vertical portion 740b of the chassis 740, and the horizontal portion of the resilient support member 780

resiliently supports the gate side flexible circuit board 718. An opening portion 740c is formed in the vertical portion 740b of the chassis 740 to fix the vertical portion of the resilient support member 780. A resilient fixing boss 760a which is inserted into the opening portion 740c is formed in the vertical portion of the resilient support member
5 760.

The vertical portion of the support member 760 can be attached to the inner side surface of the side wall portion 740b of the chassis 740 by using a double sided bonding tape instead of the opening portion 740c and the resilient fixing boss 760a.

As shown in FIG. 12, the back light assembly 720 is positioned in the mold frame
10 730, and the display unit 710 is positioned on the back light assembly 720. The end of the horizontal portion 740a of the chassis 740 is positioned along the peripheral portion of the display unit 710. The gate side flexible circuit board 718 which is attached to the gate side of the display unit 710 is folded to surround the outer side surface of the mold frame 730. A receiving recess 760 for receiving the chip of the gate side flexible circuit
15 board 718 is formed in the outer side wall portion of the mold frame 730. In the assembled state, the horizontal portion of the support member 780 supports the gate side flexible circuit board 718 so that the gate side flexible circuit board 718 is adhered to the mold frame 730.

A protecting cover 770 for covering the gate side flexible circuit board 718 is
20 provided between the gate side flexible circuit board 718 and the support member 780 to prevent the damage of the gate side flexible circuit board 718. The protecting cover 770 is fixed to the inner surface portion of the side wall 740b of the chassis 740 which is located above the support member 760, and the upper portion of the protecting cover

770 is fixed to the bottom surface of the horizontal portion 740a of the chassis 740. A bonding material 510 or a bonding tape can be used to fix the upper end of the protecting cover 770 to the bottom surface of the horizontal portion 740a of the chassis 740. The middle portion of the protecting cover 770 is surrounded to protect the gate side flexible circuit board 718. The lower end of the protecting cover 770 is fixed to the gate end of the bottom surface portion of the mold frame 730. A bonding material or a bonding tape can be used as the fixing member for fixing the lower end of the protecting cover 770.

Embodiment 5

FIG. 13 is a cross-sectional view for showing the state in which a flexible circuit board is fixed to a mold frame according to the preferred embodiment.

Referring to FIG. 13, the gate side flexible circuit board 718 is supported by using a bending piece 790 which is extended from the vertical portion 740b of the chassis 740 instead of the resilient support member 780 of FIG. 11. The bending portion 790 is extended from the vertical portion 740b of the chassis 740 which corresponds to a portion to which the gate side flexible circuit board 718 is attached. The bending piece 790 has a horizontal portion 790a which is fixed in the vicinity of the central portion of the side wall portion 740b of the chassis 740. An inclined portion 790b for resiliently supporting the gate side flexible circuit board 718 is extended at the end of the horizontal portion 790a. A support portion 790c which provides a resilient force to the inclined portion 790b is formed at the lower end of the inclined portion 790b. The support portion 790c is extended to the bottom surface of the mold frame 730 and

supports the bending piece 790. The support portion 745 has a hook shape, but can have a ring shape. The shape of the support portion 745 can be variously modified only if the support portion 745 does not generate a damage to the other members while making contact with the mold frame 730.

5 As shown in FIG. 6, the protecting cover 770 is fixed by forming a penetrating hole in the protecting cover 770 which is opposite to the bottom surface of the mold frame 730 and forming a catching boss 550 which is engaged with the penetrating hole in the mold frame 730. It is preferable that a bonding material 520 or a bonding tape is formed in the protecting cover 770 which is opposite to the bottom surface of the mold
10 frame 730.

After the liquid crystal display module is manufactured as above-mentioned, the liquid crystal display module is positioned in a front case 800 which has an opening which exposes the liquid crystal display panel 710 and a rear case 900 to finish the liquid crystal display device.

15 In the preferred embodiments, the flexible circuit board of the gate side which is manufactured by the COF method of the gate side has been explained, but the present invention can be applied to a liquid crystal display module in which a integrated printed circuit board is installed in a body and only a flexible circuit board of the COF method is attached to the data side and the gate side.

20 Various preferred embodiments for realizing the object of the present invention overlaps the gate side flexible circuit board 718 and a portion of the mold frame 730 to reduce the size and the weight of the liquid crystal display device 600.

As above-mentioned, an integrated printed circuit board is manufactured by

integrating the circuit of the gate portion and the source portion, and then is positioned on the source side of the liquid crystal panel, and the gate side flexible circuit board 718 realized by the COF method is received in a receiving recess 760 which is formed in the mold frame 730. Thus, the weight and the volume of the liquid crystal display device
5 600 can be reduced.

In the above embodiments, the liquid crystal display device which has a flexible circuit board which is attached to the gate side of the liquid display panel, is shown. However, the flexible circuit board manufactured by the COF method may be provided to the source side of the liquid crystal display device. At this time, the supporting
10 member of the present invention may also be useful for fixing the flexible circuit board towards the mold frame.

As stated above, preferred embodiments of the present invention are shown and described. Although the preferred embodiments of the present invention have been described, it is understood that the present invention should not be limited to these
15 preferred embodiments but various changes and modifications can be made by one skilled in the art within the spirit and scope of the present invention as hereinafter claimed.